

Claim 1 (Canceled)

Claim 2 (Canceled)

Claim 3 (Currently amended) The substrate for mounting an electronic part or parts thereon according to claim 26, further comprising lands which surround the opening of the hole at the side of the core substrate opposed to the side on which the electronic parts are to be mounted, and which are led to the conductor layer on the inside wall of the hole.

Claim 4 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 3, wherein the land at the side of the core substrate opposed to the side on which the electronic parts are to be mounted is connected to a wiring line at this side.

Claim 5 (Canceled)

Claim 6 (Currently amended) A substrate for mounting an electronic part or parts thereon comprising a core substrate and at least a set of insulation layer and a patterned wiring line layer which is formed on the insulation layer, said set of insulation layer and patterned wiring line layer being positioned at at least one of two opposed sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part is to be inserted, and said core substrate being provided with lands which surround an opening of each of the holes and to which the lead pin inserted in the hole is to be bonded, wherein the insulation layer or insulation layers located at at least one side of the core substrate has bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the hole surrounded by the land, at the bottom of the bores;

wherein the holes, in which the lead pin of the electronic part is to be inserted, have a closed end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted and the holes have an inside wall on which a conductor layer is formed, the conductor layer being led to the land.

Claim 7 (Previously presented) A substrate for mounting an electronic part or parts thereon comprising a core substrate and at least a set of insulation layer and a patterned wiring line layer which is formed on the insulation layer, said set of insulation layer and patterned wiring line layer being positioned at at least one of two opposed sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part is to be inserted, and said core substrate being provided with lands which surround an opening of each of the holes and to which the lead pin inserted in the hole is to be bonded, wherein the insulation layer or insulation layers located at at least one side of the core substrate has bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the hole surrounded by the land, at the bottom of the bores;

wherein at least one of the holes, in which the lead pin of the electronic part is to be inserted, has an open end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted, and at least one of the holes, in which the lead pin of the electronic part is to be inserted, has a closed end at the side of the core substrate opposed to the side on which the electronic parts are to be mounted.

Claim 8 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 6, wherein the closed end is closed by the insulation layer on the core substrate, a metal layer provided at the end of the hole, or a metal film formed during the formation of the wiring line layer.

Claim 9 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 7, wherein the closed end is closed by the insulation layer on the core substrate, a metal layer provided at the end of the hole, or a metal film formed during the formation of the wiring line layer.

Claim 10 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 6, wherein a wiring line is provided on the insulation layer at an area corresponding to the location of the hole with the closed end.

Claim 11 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 7, wherein a wiring line is provided on the insulation layer at an area corresponding to the location of the hole with the closed end.

Claim 12 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 6, further comprising a hole piercing through the core substrate and having an inside wall on which an conductor layer is provided to connect a wiring line at one side of the core substrate to another wiring line at the opposed side.

Claim 13 (Previously presented) A method of manufacturing a substrate for mounting an electronic part or parts thereon, comprising a core substrate and at least a set of insulation layer and patterned wiring line layer, which is formed on the insulation layer, at at least one sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part to be mounted is to be inserted, and being provided with lands which surround the opening of the hole and to which the lead pin inserted in the hole

is to be bonded, and holes having an inside wall on which a conductor layer is formed, the conductor layer extending to a land provided on each of the sides of the core substrate in order to connect a wiring line at one side of the core substrate to another wiring line at the opposed side, the land surrounding the opening of the hole in which a lead pin of the electronic part is to be inserted, wherein the insulation layer or layers have bores having a diameter larger than the diameter of the holes so as to expose the land and communicate with the holes, at a bottom of the bores, and the lands connected to the wiring lines are covered with the insulation layer,

the method comprising the following steps:

providing a core substrate,

forming holes piercing the core substrate,

forming, on the core substrate and around the ends of the holes, lands for the connection with the lead pin of the electronic parts to be mounted, and lands for the connection with the wiring line layers,

filling the holes with a filling material,

forming at least a set of insulation layer and patterned wiring line layer, which is formed on the insulation layer, at at least one side of the core substrate,

forming bores piercing through the resultant insulation layer or layers at the side of the core substrate on which the electronic part or parts are to be mounted, and exposing the land at the bottom of the bores, and

removing the filling material in the holes, in which a lead pin of the electronic part is to be inserted, to allow each of the holes to communicate with each of the bores.

Claim 14 (Previously presented) The method according to claim 13, wherein the formation of the bores and the removal of the filling material in the holes is carried out using a laser beam.

Claim 15 (Previously presented) The method according to claim 13, wherein the formation of the bores and the removal of the filling material in the holes is carried out by chemical etching.

Claim 16 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 7, wherein the hole, in which the lead pin of the electronic part is to be inserted, has an inside wall on which a conductor layer is formed, the conductor layer being led to the land.

Claim 17 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 16, further comprising lands which surround the opening of the hole at the side of the core substrate opposed to the side on which the electronic parts are to be mounted, and which are led to the conductor layer on the inside wall of the hole.

Claim 18 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 17, wherein the land at the side of the core substrate opposed to the side on which the electronic parts are to be mounted is connected to a wiring line at said side.

Claim 19 (Previously presented) The substrate for mounting an electronic part or parts thereon according to claim 7, further comprising a hole piercing through the core

substrate and having an inside wall on which a conductor layer is provided to connect a wiring line at one side of the core substrate to another wiring line at the opposed side.

Claim 20 (Currently amended) A substrate for mounting an electronic part or parts thereon, comprising a core substrate and at least a set of insulation layer and patterned wiring line layer, which is formed on the insulation layer, at opposed sides of the core substrate, the core substrate having holes, in each of which a lead pin of the electronic part to be mounted is to be inserted, and being provided with lands which surround an opening of the hole and to which the lead pin inserted in the hole is to be bonded, and holes having an inside wall on which a conductor layer is formed, the conductor layer being led to the land and the conductor layer extending to a land provided on each of the sides of the core substrate in order to connect a wiring line at one side of the core substrate to another wiring line at the opposed side,

wherein the insulation layer or layers have bores having a diameter larger than the diameter of the holes so as to expose the land at a bottom of the bore, said land surrounding the opening of the hole in which a lead pin of the electronic part is to be inserted such that said bore communicates with the hole, and the lands connected to the wiring lines are covered with the insulation layer.